

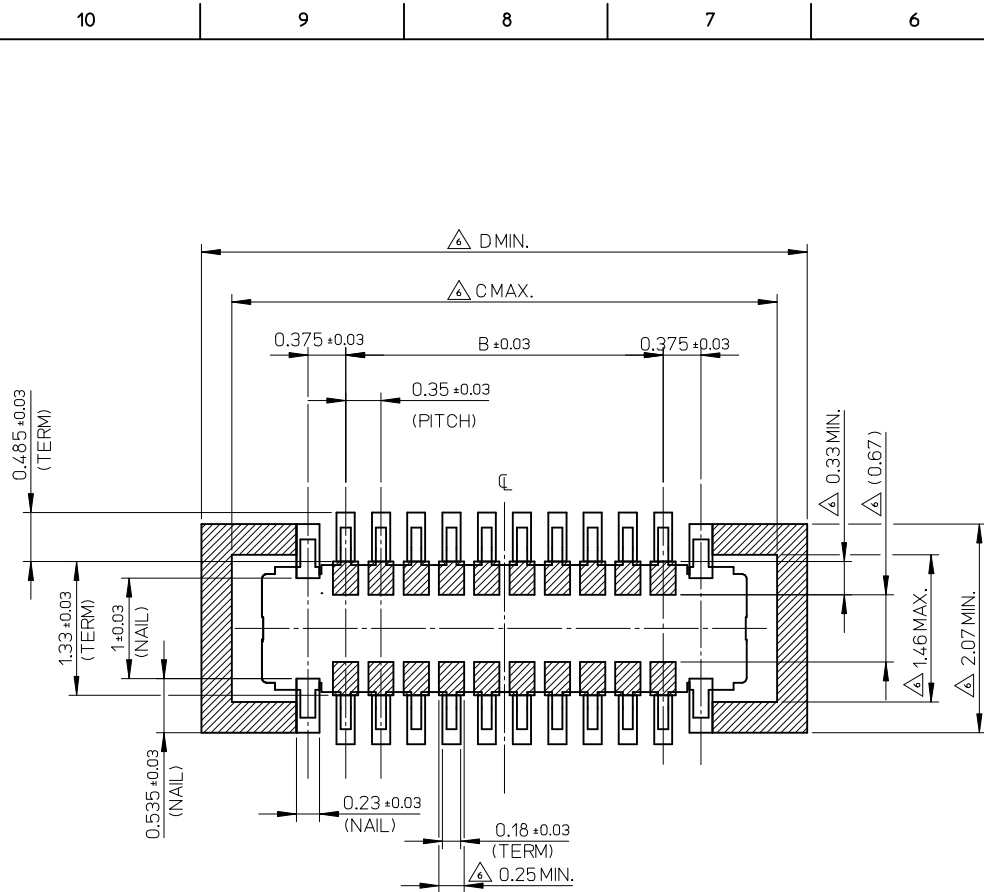
NOTES

1. MATERIAL
 WAFER : LIQUID CRYSTAL POLYMER UL94V-0(COLOR : BLACK)
 TERMINAL : COPPER ALLOY
 FITTING NAIL : COPPER ALLOY
2. PLATING
 TERMINAL :
 GOLD / UNDER PLATING : NICKEL
 *DIVIDE INTO PARTS THE GOLD PLATING OF THE CONTACT AND THE TAIL PART BY THE NICKEL PLATING.
3. FITTING NAIL :
 GOLD / UNDER PLATING : NICKEL
 *DIVIDE INTO PARTS THE GOLD PLATING OF THE CONTACT AND THE TAIL PART BY THE NICKEL PLATING.
 *EVEN THOUGH GOLD PLATING ON THE TOP SURFACE OF NAIL MIGHT BE THIN, NO FUNCTIONAL PROBLEM.
4. APPLY FOR (CIRCUIT/2)=EVEN.
5. MATE WITH : 505066-**10
6. TAIL AND FITTING NAIL COPLANARITY TO BE 0.08MAXIMUM.
7. PROHIBITED AREA OF PATTERN WIRING AND SOLDER.
 (FOR EACH AREA, THE WIRING THAT TOUCHES ON THE SOLDER CAN BE ATTACHED, THEN COVERED WITH A FILM TO KEEP SOLDER OUT.)
8. ELV and RoHS COMPLIANT.

3.56	2.96	0.70	2.36	505070-0610	O	---	6
D	C	B	A	EMBOSSD TAPE PACKAGE	HIGH VOL. TOOL	LOW VOL. TOOL	CIRCUIT
				ORDER NO.	SAMPLE PREPARATION O : TOOLED Δ : WORK IN PROCESS --- : TOOLING TO BE CONFIRMED		

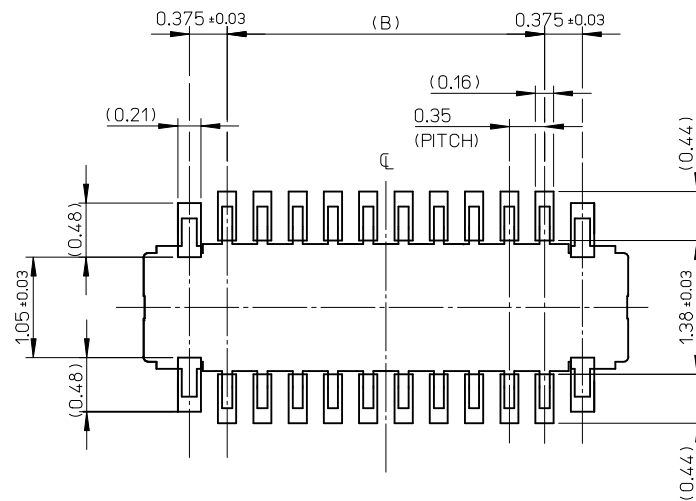
CONNECTOR SERIES No. : 505070-**09

REVISED EC NO: J2016-1010 DRWN:MIT001 CHKD:TASAKAWA APPR:KMORIKAWA	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 20:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	±0.03	DRAWN BY	DATE	TITLE		
	0.25 OVER 0.5 UNDER	±0.05	KSASAKI	2014/04/15	0.35 BB CONN. H=0.6 SSB6 RP PLUG ASSY		
	0.5 OVER 1.0 UNDER	±0.1	CHECKED BY	DATE	molex DOCUMENT NO. SD-505070-001 SHEET NO. 1 OF 2		
1.0 OVER 30 UNDER	±0.2	KTANAKA03	2014/04/15				
30 OVER	±0.25	APPROVED BY	DATE				
	±0.3	KMORIKAWA	2014/05/02				
	ANGULAR ±1 °	MATERIAL NO.		SEE CHART			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



RECOMMENDED P.W.BOARD PATTERN LAYOUT (REFERENCE)

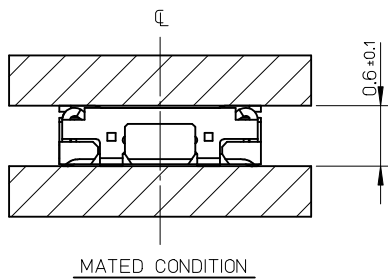
△ PROHIBITED AREA OF PATTERN WIRING AND SOLDER.
(FOR EACH AREA, THE WIRING THAT TOUCHES ON THE SOLDER
CAN BE ATTACHED, THEN COVERED WITH A FILM TO KEEP SOLDER OUT.)



RECOMMENDED METAL MASK LAYOUT (REFERENCE)

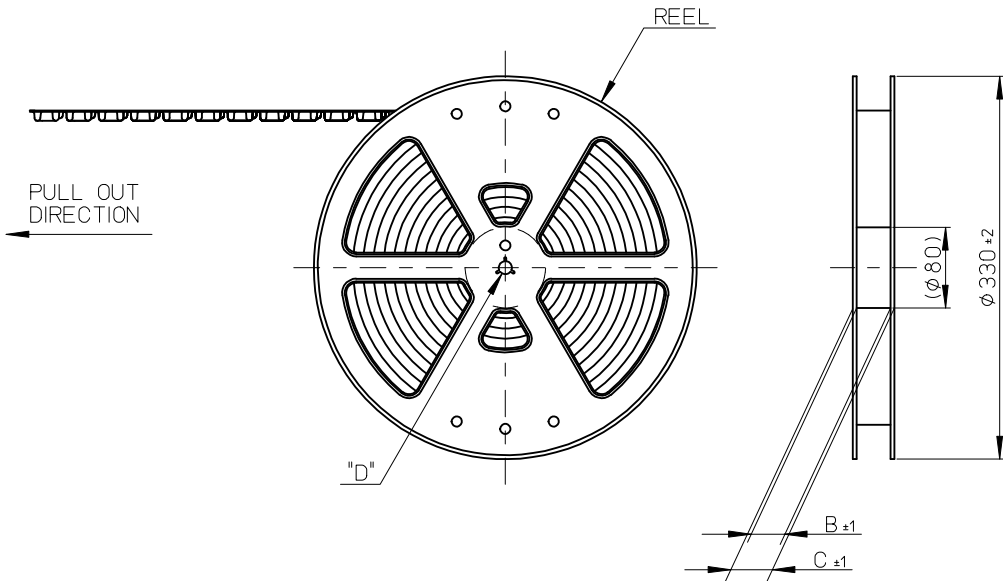
RECOMMENDED THICKNESS OF METAL MASK : t=0.08mm

RECOMMENDED OPEN APERTURE RATIO OF METAL MASK : 80%



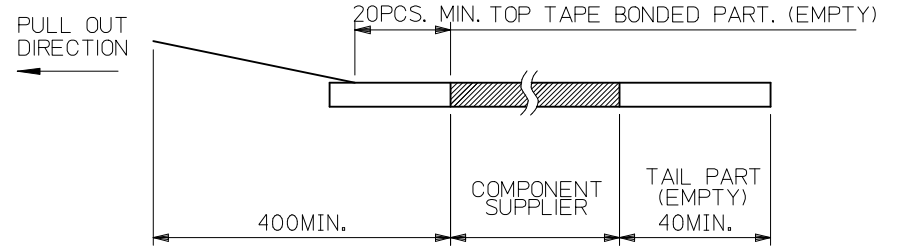
MATED CONDITION

REVISED EC NO: J2016-1010 DRWN:MIT001 2016/03/30 CHKD:TASAKAWA 2016/03/30 APPR:KMORIKAWA 2016/03/31	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 20:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	0.25 UNDER	± 0.03	DRAWN BY KSASAKI	DATE 2014/04/15	TITLE 0.35 BB CONN. H=0.6 SSB6 RP PLUG ASSY			
	0.25 OVER 0.5 UNDER	± 0.05	CHECKED BY KTANAKA03	DATE 2014/04/15				
	0.5 OVER 1.0 UNDER	± 0.1	APPROVED BY KMORIKAWA	DATE 2014/05/02				
	1.0 OVER 30 UNDER	± 0.25	MATERIAL NO. SEE SHEET1		DOCUMENT NO. SD-505070-001	SHEET NO. 2 OF 2		
30 OVER	± 0.3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

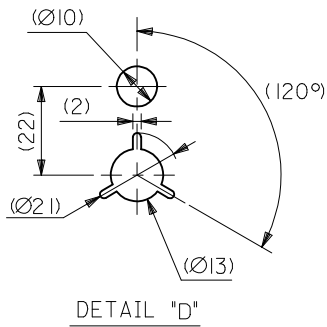


NOTES

1. RE DETAILED DIMENSION, SEE PRODUCT DRAWING.
2. NUMBER OF CONNECTORS : 3000PCS/REEL
3. LEAD TAPE LENGTH

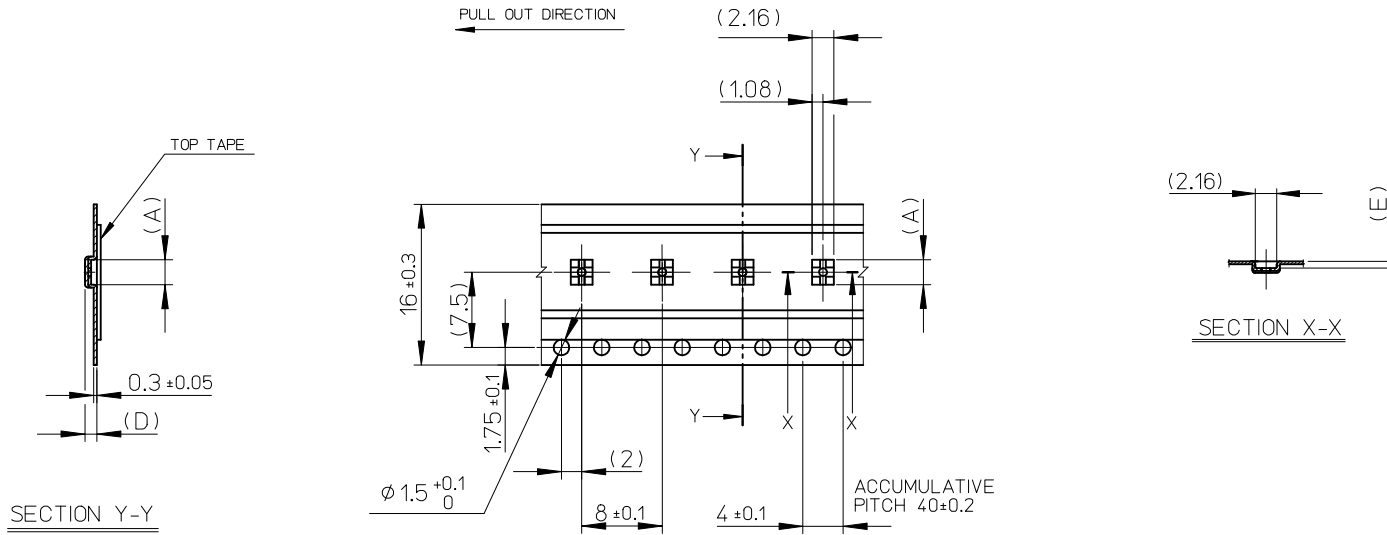


4. TOP TAPE PEEL FORCE IS DEFINED BY IEC60286-3.
5. MATERIAL
 CARRIER TAPE : POLYSTYRENE
 TOP TAPE : PET , OTHER
 REEL : POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>
6. ELV AND RoHS COMPLIANT



DETAIL "D"

REVISED EC NO: J2016-1010 DRWN:MITO01 2016/03/30 CHKD:TASAKAWA 2016/03/30 APPR:KMORIKAWA 2016/03/31	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		MODEL NO.	505066-***10
	0.25 UNDER		MM ONLY		DESIGN UNITS	METRIC
	0.25 OVER 0.5 UNDER		DRAWN BY DATE		THIRD ANGLE PROJECTION 0.35 BB CONN. H=0.6 SSB6 RP PLUG ASSY EMBSTP PKG	
	0.5 OVER 1.0 UNDER		KSASAKI 2014/03/10			
	1.0 OVER 10 UNDER		CHECKED BY DATE		molex SD-505070-002	
	10 OVER 30 UNDER		KTANAKA03 2014/03/10			
30 OVER		APPROVED BY DATE		DOCUMENT NO.	SHEET NO.	
ANGULAR ±1 °		KMORIKAWA 2014/08/01		SEE CHART	1 OF 2	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
REV	SIZE					
	A3					



16	0.66	1.16	21.4	17.4	2.43	505070-0610	0	---	6						
キャリアテープ幅 CARRIER TAPE WIDTH							(E)	(D)	C	B	(A)	MATERIAL No.	HIGH VOL. TOOL	LOW VOL. TOOL	CIRCUIT
											SAMPLE PREPARATION				

REVISED EC NO: J2016-1010 DRWN: ITO01 2016/03/30 CHKD: TASAKAWA 2016/03/30 APPR: KMORIKAWA 2016/03/31	GENERAL TOLERANCES (UNLESS SPECIFIED)				DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
	0.25 UNDER				± 0.03	DRAWN BY	DATE	TITLE			
	0.25 OVER	0.5 UNDER			± 0.05	KSASAKI	2014/03/10	0.35 BB CONN. H=0.6 SSB6 RP PLUG ASSY EMBSTP PKG			
	0.5 OVER	1.0 UNDER			± 0.1	CHECKED BY	DATE				
	1.0 OVER	10 UNDER			± 0.2	KTANAKA03	2014/03/10	molex DOCUMENT NO. SD-505070-002 SHEET NO. 2 OF 2			
10 OVER	30 UNDER			± 0.25	APPROVED BY	DATE					
30 OVER				± 0.3	MATERIAL NO.						
ANGULAR ±1 °				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART					
		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							